PALLADIUM SURFACE COATINGS SUITABLE FOR WIREBONDING AND PROCESS FOR FORMING PALLADIUM SURFACE COATINGS

Abstract of the Invention

A surface finish which provides improved wirebonding performance for integrated circuit packages is disclosed. The surface finish which is formed on a substrate includes a palladium layer and one or more material layers. The one or more material layers are interposed between the substrate and the palladium layer. The palladium layer has a hardness that is less than about 500 (KHN_{50}) while at least one material layer has a hardness that is less than about 250 (KHN_{50}).

This Sheet Has Been Replaced

